

产品规格书

DATA SHEET

客户名称 : _____
产品名称 : 单相贴片整流桥
产品型号 : MB*F 整流桥
产品描述 : 玻璃钝化芯片整流桥
0.8A (100~1000V)
物料编码 : 无

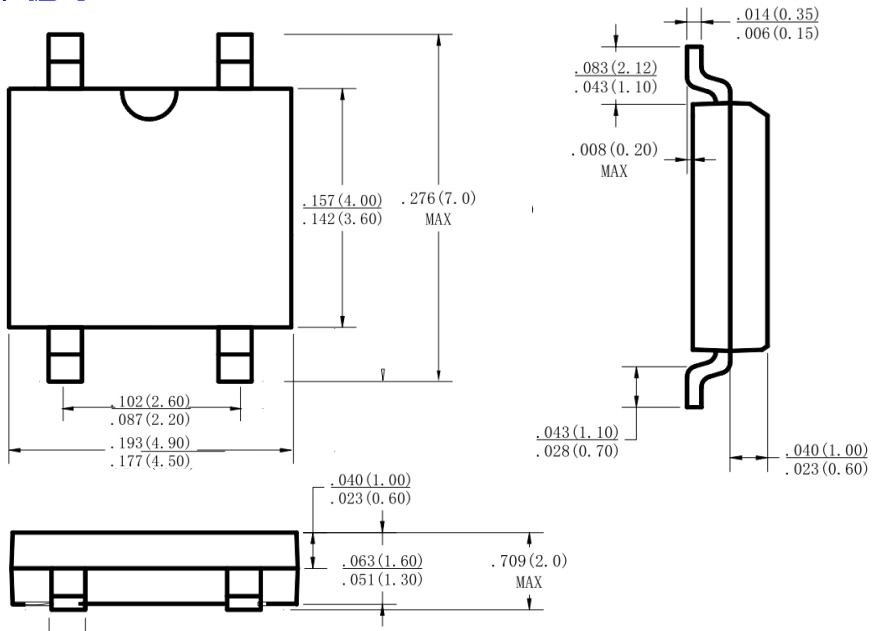
客户确认 Customer Signature

乐山希尔电子股份有限公司

中国，四川省，乐山市高新技术开发区南新路 9 号 (614000)

网址 : www.share-leshan.com.cn 邮箱 : Sales@share-leshan.com.cn

0.8A Glass Passivated Single-Phase Bridge Rectifier

特征 / Features	外形尺寸/Outline Dimensions
玻璃钝化芯片 Glass passivated chip 低反向漏电流 Low Reverse Leakage Current 高耐浪涌电流能力 High surge current capability	<p>Case: MB*F</p>  <p style="text-align: right;">Dimensions in inches and (millimeters)</p>
机械参数 / Mechanical Data	
本体: 塑封 Case: Molded plastic case 标识/极性: 本体标记 Marking / Polarity: Marked on Body 重量: 约0.075克 Weight: About 0.075 grams	

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	MB*F						单位 Unit
		1	2	4	6	8	10	
VRRM	最大反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage	100	200	400	600	800	1000	V
Io (AV)	平均整流输出电流 Average Forward Output Rectified Current	60Hz 正弦波, 电阻负载, Ta=25°C 60Hz, sine wave R-load, Ta=25°C					0.8 (note1)	A
							0.5 (note2)	
VF	正向峰值电压 Forward Voltage Per Leg @IFM =0.4A	Max=0.95						V
IFSM	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	30						A
IR	反向漏电流 Maximum DC reverse current at rated TJ =25°C DC blocking voltage per leg TJ = 125°C	Max=10 Max=40						uA
i2t	热容值 Rating for fusing (t<8.3ms)	3.7						A²S
RθJA	热阻 Maximum thermal resistance per leg	62 (note1)						°C/W
		134 (note2)						
RθJC		20 (note3)						
Tj	结温 Operating junction Temperature	150						°C
TSTG	存储条件 Storage Temperature	-55 ~ +150						°C

note:

1. 安装在氧化铝基板上 (On alumina substrate)
2. 安装在玻璃-环氧基板上 (On glass-epoxy substrate)
3. 结和引线之间 (Between junction and lead)

特性曲线 / Characteristics Curves

图1: I_o - T_a 曲线
FIG1: I_o - T_a Curve

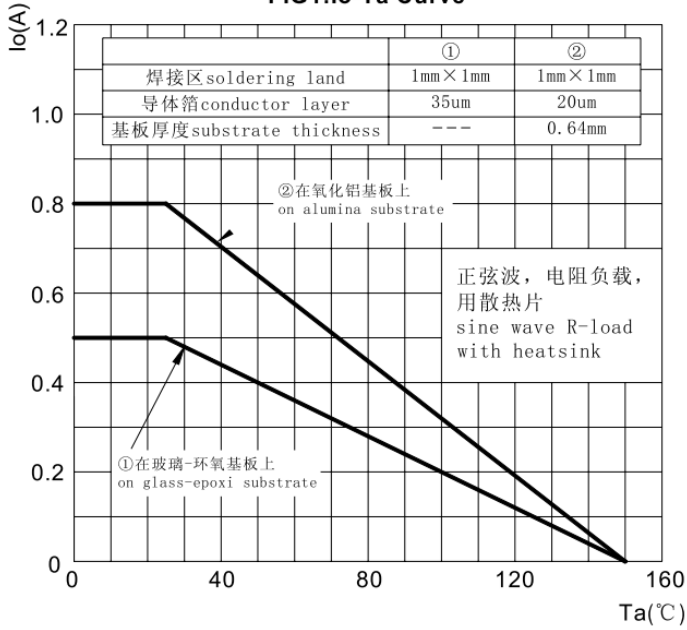


图2: 耐正向浪涌电流曲线
FIG2:Surge Forward Current Capadity

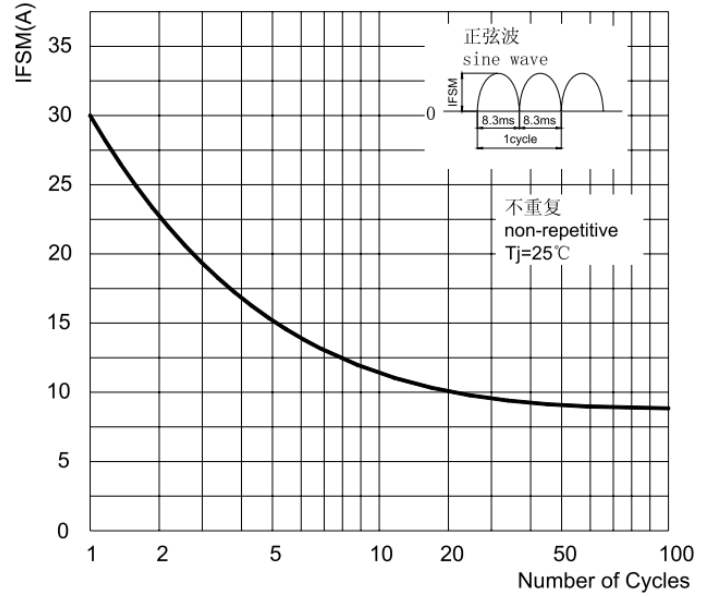


图3: 正向电压曲线
FIG3: Forward Voltage

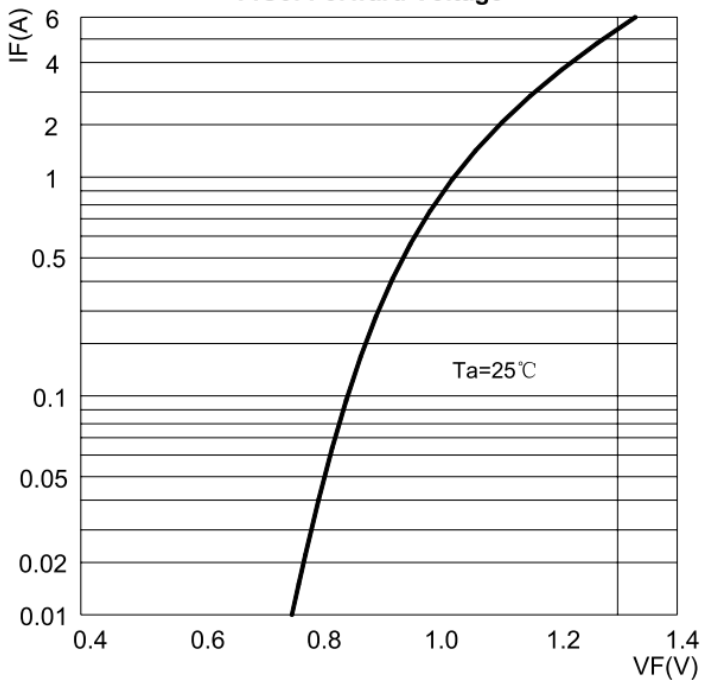


图4: 反向电流曲线
FIG4:Typical Reverse Characteristics

